


Date: 4/25/2021

Material Number: EFR32FG1P131F256IM32-C0R

Pkg Config.: PK1271

Detailed Device Composition 									
No.	Homogeneous Material	Material Weight (mg)	Material Content	CAS Number	Material Weight (%)	Material Weight (mg)	ppm of Material	Wt % of Total Unit	ppm of Total Unit
1	Mold Compound	32.50	Carbon Black	1333-86-4	0.400	0.130	4000	0.1959	1959
			Epoxy Resin (Proprietary)	Proprietary	7.000	2.275	70000	3.4277	34277
			Metal Hydroxide	Proprietary	2.000	0.650	20000	0.9793	9793
			Phenol Resin (Proprietary)	Proprietary	5.000	1.625	50000	2.4484	24484
			Silica (Amorphous) B	60676-86-0	85.600	27.820	856000	41.9159	419159
2	Plating - External	2.20	Tin	7440-31-5	100.000	2.200	1000000	3.3147	33147
3	Bond Wire	0.48	Copper	7440-50-8	96.550	0.463	965500	0.6983	6983
			Gold	7440-57-5	0.350	0.002	3500	0.0025	25
			Palladium	7440-05-3	3.100	0.015	31000	0.0224	224
4	Die Attach Epoxy	8.60	Acrylate monomer 10089	TS ref# 10089	5.000	0.430	50000	0.6479	6479
			Acrylate monomer 10123	TS ref# 10123	5.000	0.430	50000	0.6479	6479
			Acrylate monomer 10283	TS ref# 10283	5.000	0.430	50000	0.6479	6479
			Bismaleimide monomer	TS ref# 10049	5.000	0.430	50000	0.6479	6479
			Silver	7440-22-4	80.000	6.880	800000	10.3660	103660
5	Leadframe	19.90	Chromium	7440-47-3	0.270	0.054	2700	0.0810	810
			Copper	7440-50-8	98.850	19.671	988500	29.6382	296382
			Silver	7440-22-4	0.430	0.086	4300	0.1289	1289
			Tin	7440-31-5	0.250	0.050	2500	0.0750	750
			Zinc	7440-66-6	0.200	0.040	2000	0.0600	600
6	Die	2.69	Silicon	7440-21-3	99.800	2.686	998000	4.0464	40464
			Silicon Dioxide	60676-86-0	0.200	0.005	2000	0.0081	81
	Total Unit Weight =	66.37				66.37		100.0000	1000000